MESSRS.

SPECIFICATION FOR APPROVAL
承 认 书

Product	**ELECTRET CONDENSER MICROPHONE**
Part No.	**AMF-O97L45-DB(RoHS)**
Customer Part No.	
Customer Approval	

Approved By	Checked By	Made By
王台平 FEB-28-2013	曹丽萍 FEB-28-2013	LILY FEB-28-2013

常 州 华 龙 电 子 有 限 公 司
DRAGONSTATE ELECTRONIC CORPORATION

中国江苏省常州市新区电子园新四路 36 号
Tel: +86-519-85110078. 86-519-85106698, Fax: +86-519-85101081

EDITION:1.1

1. 变更记录（History change record）

Change Items	Date	Note	Drawn by	Checked by
	2012-08-15	First Issue	Lily	王台平 2012-08-15

2. 储藏与判断条件 (Storage And Judgement Conditions)

	Temperature Range(°C)	Rel. Humidity(%)	Static Pressure(kPa)
Judgement	19~21	60~70	86~106
Storage	-25~70		
Operating	-25~70		

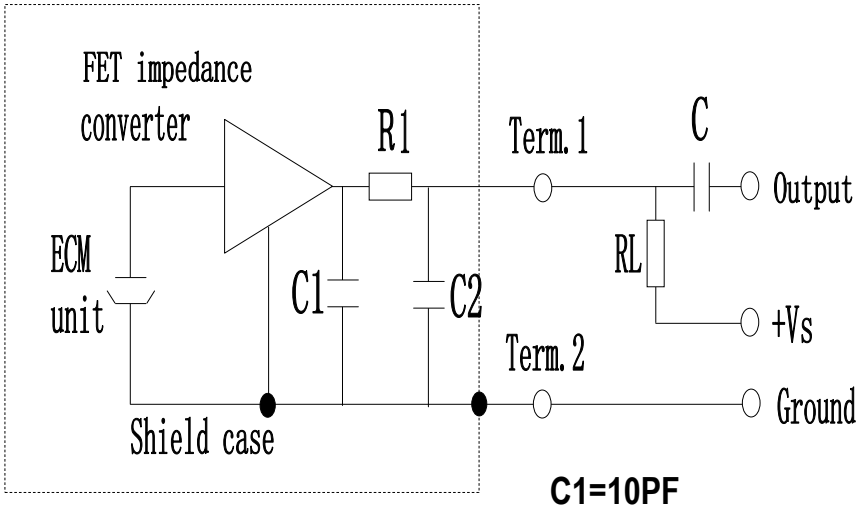
3. 规格 (Specifications)

Test conditions(V_S=3.0V R_L=2.2kΩ Temp=20±2℃ R.H=60±5%)

Item	Symbol	Test Conditions	Min	Standard	Max	Unit
灵敏度 Sensitivity	S	f=1kHz,Pin=1Pa	-47	-45	-43	dB (0dB=1V/Pa)
阻抗 Impedance	Z	f=1kHz,Pin=1Pa			2.2	kΩ
指向性 Directivity	Omni-directional					
消耗电流 Current Consumption	I		150		500	μA
工作电压 Operation Voltage Range	U		1.0	3.0	10	V
信噪比 S/N Ratio	S/N(A)	f=1kHz,Pin=1Pa A Curve	58			dB
降压特性 Decreasing Voltage Characteristic	ΔS	f=1kHz,Pin=1Pa V_S=2.0-1.5V			-3	dB
最大输入声压级 Max.Input Sound Level	MISPL	f=1kHz Distortion<1%			110	dB

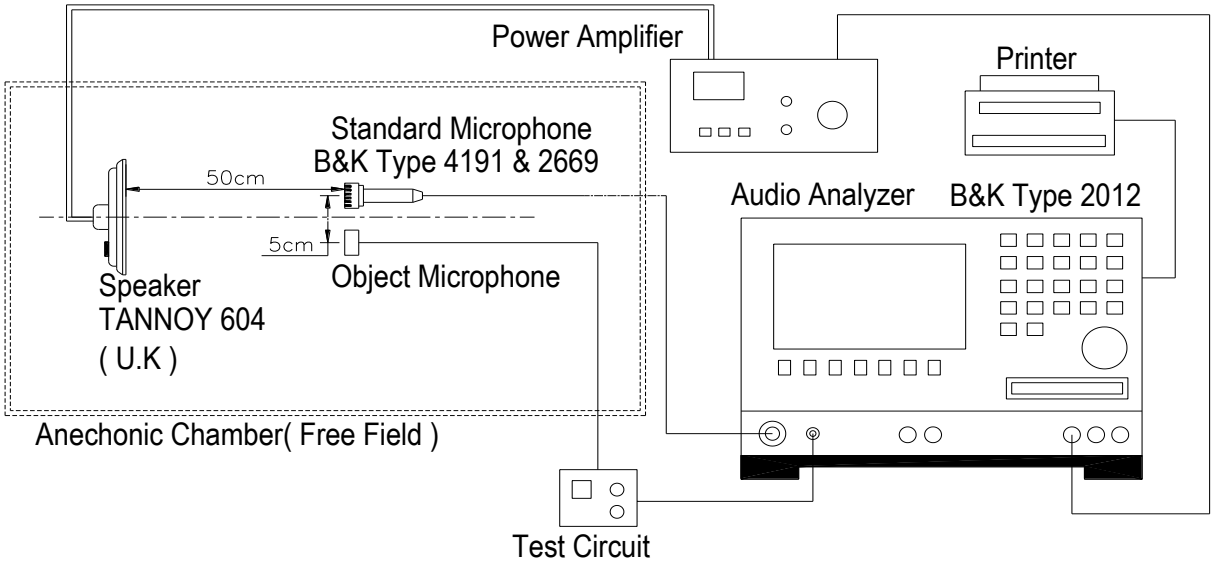
4. 测试电路（Standard Test Circuit）

Vs=3.0V RL=2.2kΩ Te=20℃ R.H.=60%

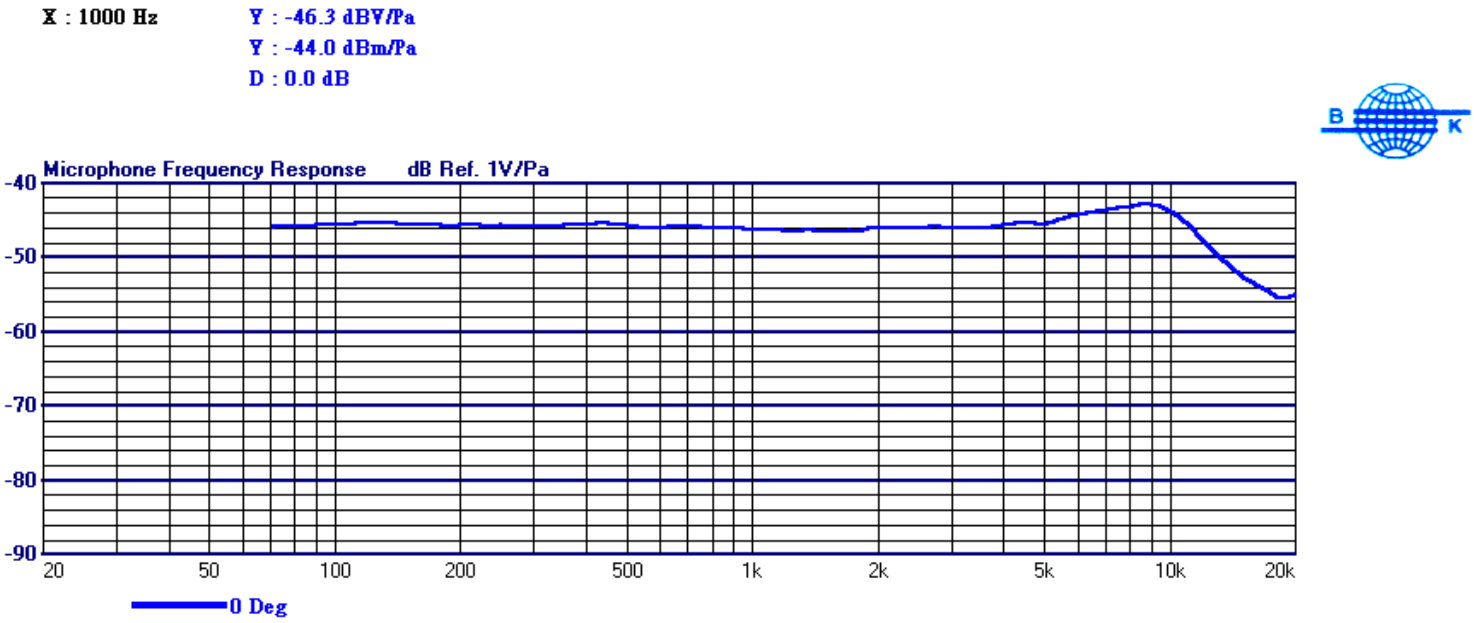


C1=10PF
C2=33PF
R1=330Ω

5. 测试装备图（Standard Test Fixture）

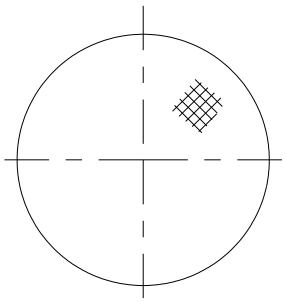


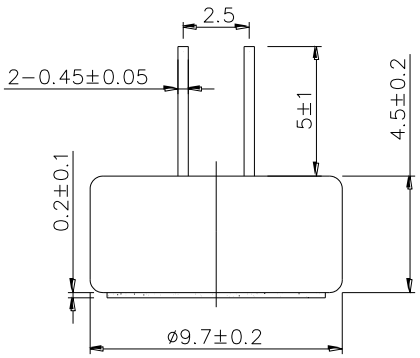
6 频响曲线（Frequency Response Curve）

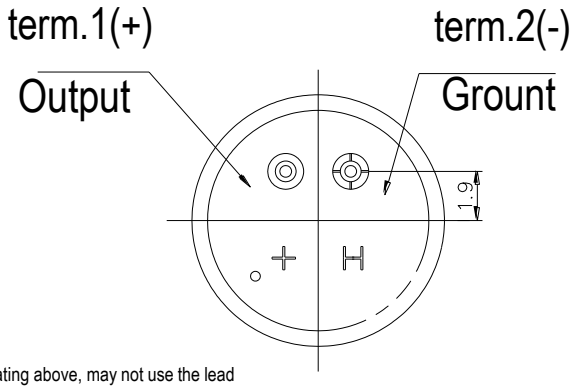


7.外观图（Appearance Drawing）

REV NO.	REVISION NOTE	APPROVAL	DATE







Sn-2Bi ＊The plating above, may not use the lead

TITLE:	MICROPHONE		DRAWN: Lily 2012/08/20	SCALE: 4/1	SHEET: 1 : 1
PART NO.	AMF−097L45−DB	1	DESIGNED: R & D OF D.S.	UNITS: mm	
DWG NO.	DTM−1079	REV	CHECKED: Emily	TOLERANCE ± 0.2	
			APPROVAL: Eric	UNLESS OTHERWISE SPECIFIED: ONE PLACE DECIMAL ± *** TWO PLACE DECIMAL ± *** THREE PLACE DECIMAL ± ***	
			MATERIAL: *****		

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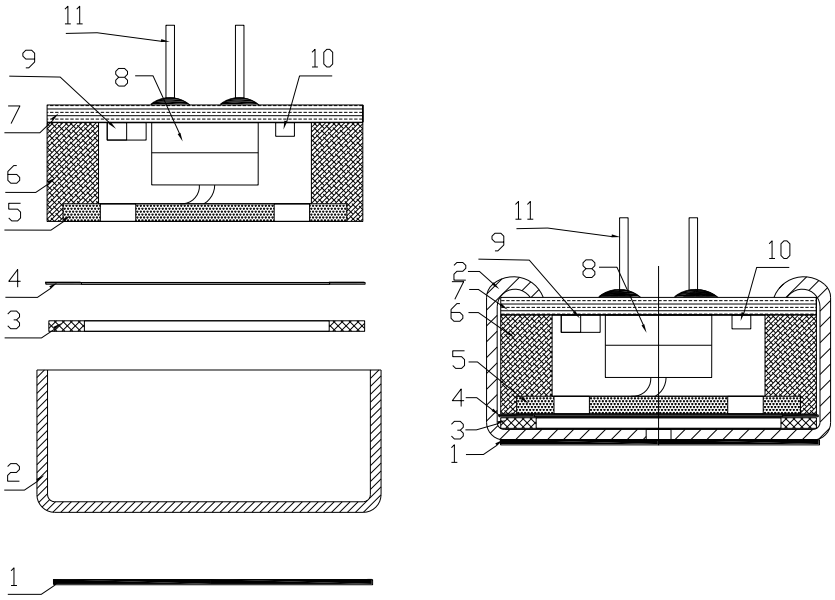
8.结构图（Appearance Drawing）



11	PIN		2	
10	Chip Capacitor		1	10+33PF
9	RESISTANCE		2	330 Ω
8	FET		1	
7	PCB	FR4	1	
6	Chamber		1	
5	Electret Plate		1	
4	Spacer		1	
3	Diaphragm		1	
2	Case	Al-Mg alloy	1	
1	Dustproof gauze	Non-weave cloth	1	
No.	**Name**	**material**	**QTY**	**Remark**

9.可靠性试验 (Reliability Test)

在下列试验完成后,在温度为 20℃,相对湿度为 65%的条件下恢复 3 小时后进行测试,灵敏度与初始灵敏度相差在±3dB 以内.

(All tests should be done after 3 hours of conditioning at 20℃, R.H65%, while the sensitivity is to be within ± 3dB,from the initial sensitivity after the following experiments.)

9.1 高温试验 (HIGH TEMPERATURE TEST)

温度(High temperature): +60℃

放置时间(Duration): 200hours

9.2 低温试验 (LOW TEMPERATURE TEST)

温度(Low temperature): -25℃

放置时间(Duration): 200 hours

9.3 温度循环试验(如图 1) (TEMPERATURE CYCLE TEST)(See in Fig.1)

低温(Low temperature): -25℃

高温(High temperature): +70℃

转化时间(Changeover time): 10min

放置时间(Duration): 30min

次数(Cycle): 5

9.4 湿度 (STATICAL HUMIDITY TEST)

温度(Temperature): +40℃

相对湿度(Relative humidity): 90～95%

放置时间(Duration): 200 hours

9.5 振动试验 (VIBRATION TEST)

振幅(Amplitude):	1.52mm
持续时间(Duration):	1 分钟/面(minutes/plane)
频度范围(Freq.range):	10～55Hz
试验时间(Total time):	2 小时(hour)

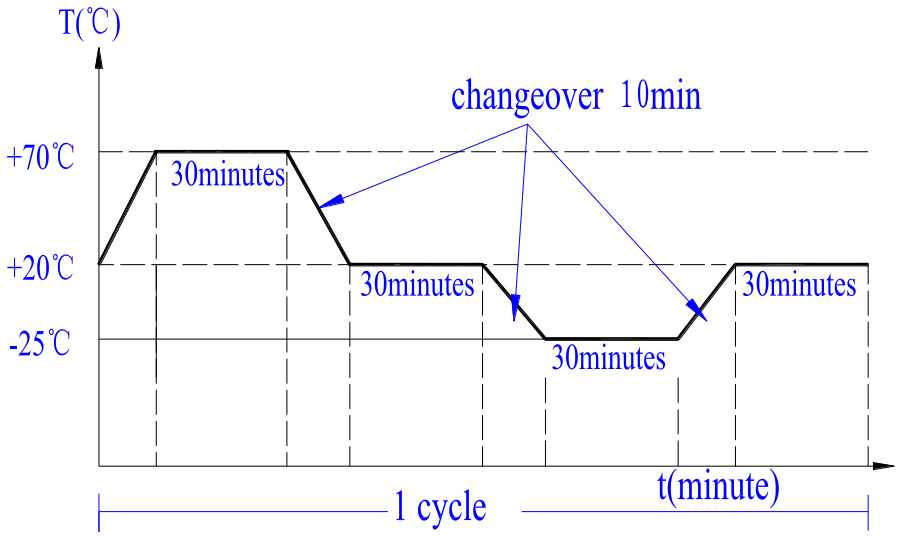
9.6 跌落试验 (DROP TEST)

不带包装的跌落到 20mm 厚的地板上(Drop a unit unpacked onto a board of 20mm thick)

高度(Height):	1 m
次数(Cycle):	6 (1 each plane)

9.7 静电测试 (ESD TEST)

在两次无杂质的静电释放暴露中放电.(接触:±8kV,空气:±15 kV)麦克风在 10 次暴露后无干扰 The microphone under test must be discharged between each ESD exposure without ground. (contact:±8 kV, air:±15 kV)There is no interference in operation after 10 times exposure.



10. 焊接要求 (Regarding the Soldering operation)

每个驻极体电容传声器在其麦克风上都有一个 FET,这种 FET 在过热和电流撞击时易损坏，所以对于焊接应遵

循以下操作：

- 要求使用 25W-35W 烙铁，并保持 300±10℃的温度范围 .
- 在每一个端的焊接应在 2 秒内完成，以防过热 .
- 禁止单体麦克风焊接 .(否则会影响驻极体电容传声器的灵敏度)
- 最理想的散热装置按以下设计.

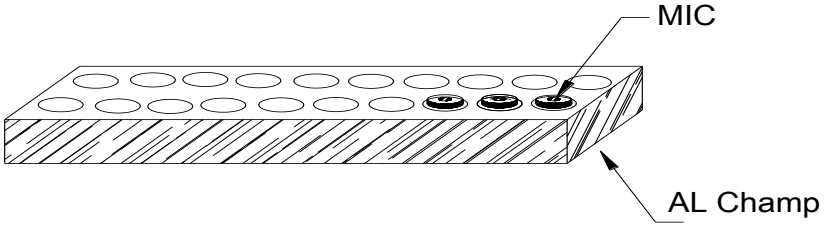
Every ECM contains a FET with microphone body.
This FET easy to damageable from excessive heat and electrical shock. Proper attention for the soldering work is

required same as followings.

- Recommend to use 25W-35W ceramic soldering iron and apply 300±10℃ temperature range
- Soldering should be accomplished within 2 seconds at each terminal so as not to be overheated.
- Do not make a cavity at the surface of lead lump on the PCB. wiring board.

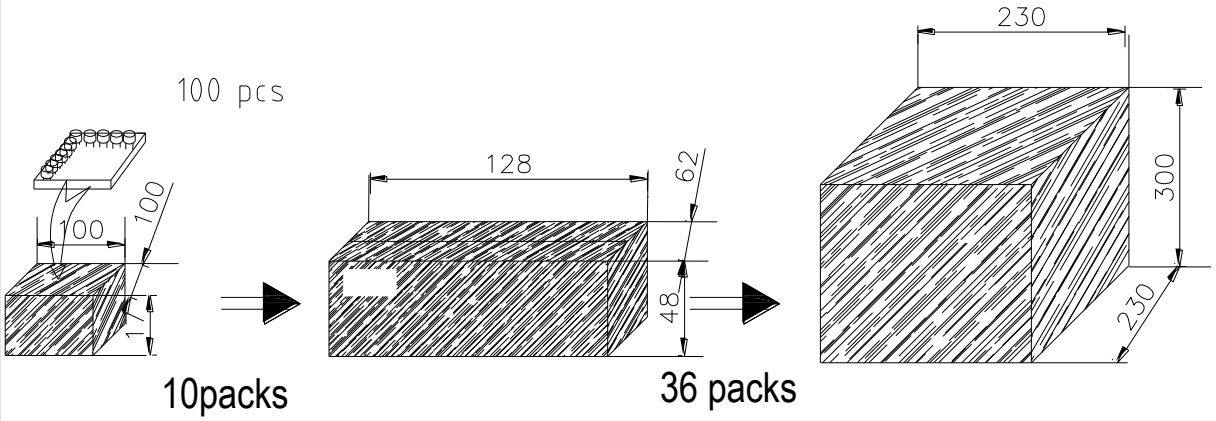
(Opened cavity will influence to the sensitivity of ECM)

- Optimal design for heat sink pad is same as below.



11.包装规格 (Packing Specifications)

REV NO.	REVISION NOTE	APPROVAL	DATE



100pcs per plastic bag
N/W:70g G/W:72g
MODEL:
QTY:100PCS
LOT NO:

1000pcs per plastic box
N/W:700g G/W:780g
MODEL:
QTY:1000PCS
LOT NO:

12000pcs per out bag
N/W:8.4kG G/W:11.4kG
MODEL:
QTY:12000PCS
LOT NO:

TITLE: packing		DRAWN: Lily 2009/03/16	SCALE: 5/1 SHEET: 1 : 1
PART NO.	1	DESIGNED: R & D OF D.S.	UNITS: mm
		CHECKED: Emily	TOLERANCE ± 0.2
DWG NO.		APPROVAL: Eric	UNLESS OTHERWISE SPECIFIED: ONE PLACE DECIMAL ± *** TWO PLACE DECIMAL ± *** THREE PLACE DECIMAL ± ***
	REV	MATERIAL: *****	

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